

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☐ WHITE

☐ RED

☐ BLACK

☒ Blue ink PANTONE 2955

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

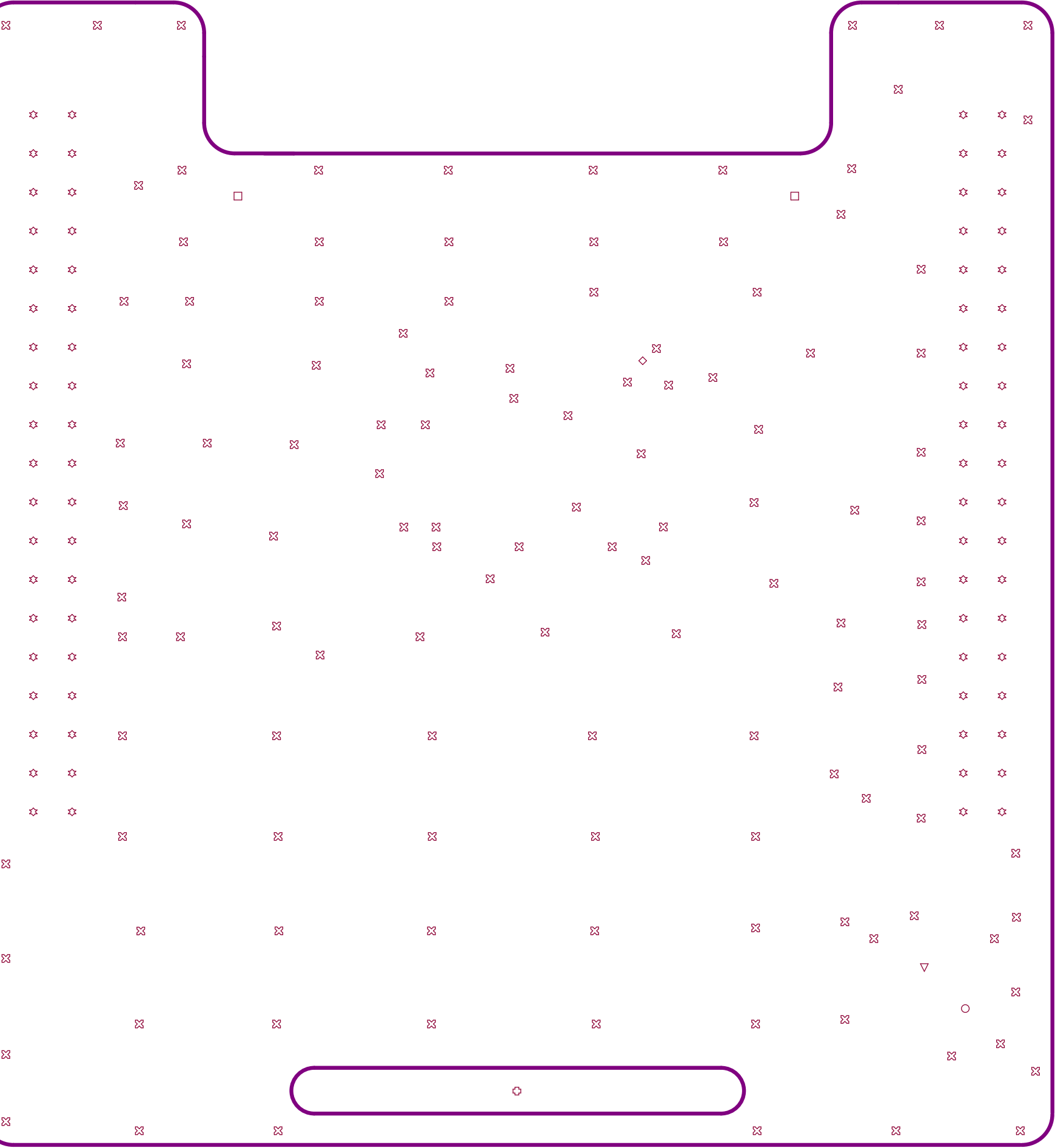
PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.21mm
GAPS : 0.21mm



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer	Copper	0.035mm		
	Dielectric 1	FR-4	1.500mm	4.2	
2	Bottom Layer	Copper	0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Hole Length	Routed Path Length
◆	1	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h30m0mx0	-	-
▽	1	0.800mm (31.50mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn80m85p1000	-	-
○	1	1.100mm (43.31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn110m115p1000	-	-
⊕	1	3.000mm (118.11mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r3000_300hn300_3000r100	30.000mm (1181.10mil)	27.000mm (1062.99mil)
□	2	1.200mm (47.24mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn120m125	-	-
☆	76	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
✕	123	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h40m0mx0	-	-
	205 Total									

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout